

Electronic Module Industry



Overview

Power Module Market Size and Forecast (2021 - 2034), Global and Regional Share, Trend, and Growth Opportunity Analysis Report Coverage: By Material (Silicon (SI), Silicon Carbide (SIC), Gallium Nitride (GAN), and Others), Industry Vertical (ICT, Automotive & Transportation. Power Module Market Size and Forecast (2021 - 2034), Global and Regional Share, Trend, and Growth Opportunity Analysis Report Coverage: By Material (Silicon (SI), Silicon Carbide (SIC), Gallium Nitride (GAN), and Others), Industry Vertical (ICT, Automotive & Transportation. Today, the leading power module suppliers are mainly located in Europe and Japan. They include Infineon Technologies, Semikron Danfoss, STMicroelectronics, Fuji Electric, Mitsubishi Electric, and Rohm. 12 Billion in 2026 and eventually reaching USD 1114. I need the full data tables, segment breakdown, and competitive landscape for detailed regional analysis and revenue. Power Module Packaging Market Report is Segmented by Components (Substrate, Die Attach, Substrate Attach, Encapsulations, Interconnections, and More), Power Device Type (IGBT Modules, Si-MOSFET Modules, Sic Modules, Gan Modules, and More), Power Range (Below 600 V, 600-1, 200 V, 1, 200-1, 700 V. The global power module market is expected to reach an estimated \$15 billion by 2030 with a CAGR of 13% from 2024 to 2030. The major drivers for this market are the major drivers for the growth of this market are high growth of electric vehicles, increasing focus of consumers for minimizing power.



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Power Module Packaging Market

Infineon Technologies AG, Mitsubishi Electric Corporation (Powerex Inc.), Fuji Electric Co. Ltd., Semikron-Danfoss GmbH & Co. KG and ON

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The global power electronics module market is segmented on the basis of type, material, voltage, industry vertical, and region. Based on type, the power electronics module market is categorized into

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